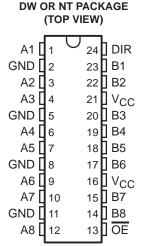
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- State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}
- Designed to Facilitate Incident-Wave Switching for Line Impedances of 25 Ω or Greater
- Distributed V_{CC} and GND Pins Minimize Noise Generated by the Simultaneous Switching of Outputs
- Data Flow-Through Pinout (All Inputs on Opposite Side From Outputs)
- High-Impedance State During Power Up and Power Down
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015
- Package Options Include Plastic Small-Outline (DW) Packages and Standard Plastic 300-mil DIPs (NT)



description

The SN64BCT25245 is a 25- Ω octal bus transceiver designed for asynchronous communication between data buses. It improves both the performance and density of 3-state memory address drivers, clock drivers, and bus-oriented transceivers.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can disable the device so that both buses are effectively isolated.

This transceiver is capable of sinking 188-mA I_{OL} , which facilitates switching 25- Ω transmission lines on the incident wave. The distributed V_{CC} and GND pins minimize switching noise for more reliable system operation.

The outputs are in a high-impedance state during power up and power down while the supply voltage is less than approximately 3 V.

The SN64BCT25245 is characterized for operation from -40°C to 85°C and 0°C to 70°C.

FUNCTION TABLE

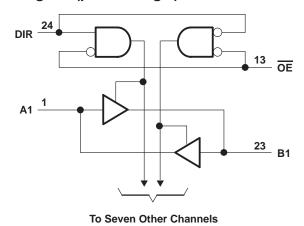
INP	UTS	
ŌĒ	DIR	OPERATION
L	L	B data to A bus
L	Н	A data to B bus
Н	Χ	Isolation

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logic symbol†

OE G3 24 DIR 3EN1[BA] 3EN2[AB] 23 **▽ 1** В1 \triangleright 2∇ 22 **A2 B2** 20 **A3 B3** 6 19 Α4 **B**4 18 Α5 **B5** 9 17 A6 **B6** 10 15 **B7 A7** 14 12 **A8** В8

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1): Control inputs	0.5 V to 7 V
I/O ports	–0.5 V to 5.5 V
Voltage range applied to any output in the disabled or power-off state, VO	0.5 V to 7 V
Voltage range applied to any output in the high state, V _O (B port)	–0.5 V to V _{CC}
Input clamp current, I _{IK}	–30 mÅ
Current into any output in the low state, IO: A port	376 mA
B port	48 mA
Operating free-air temperature range	–40°C to 85°C
Storage temperature range	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

			MIN	NOM	MAX	UNIT	
Vсс	Supply voltage	4.5	5	5.5	V		
V _{IH}	High-level input voltage		2			V	
VIL					8.0	V	
Ι _{ΙΚ}	Input clamp current				-18	mA	
	High level autout august	A port			-80	A	
IOH	High-level output current	B port			-3	mA	
	Law law law taut amount	A port			188	^	
lOL	Low-level output current B port				24	mA	
TA	Operating free-air temperature				85	°C	

[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

NOTE 1: The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST	MIN	TYP†	MAX	UNIT			
٧ıK		V _{CC} = 4.5 V,	I _I = -18 mA				-1.2	V	
	A	$V_{CC} = 4.75 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.7				
∨он	A port	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -80 \text{ mA}$		2			V	
	B port	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.4	3.3			
	A == ===	V 45V	I _{OL} = 94 mA			0.42	0.55		
VOL	A port	$V_{CC} = 4.5 \text{ V}$	I _{OL} = 188 mA				0.7	V	
	B port	$V_{CC} = 4.5 \text{ V},$	I _{OL} = 24 mA			0.35	0.5		
		V 045 0 0 V (5 000 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	V _O = 2.7 V				70	μΑ	
		$V_{CC} = 0$ to 2.3 V (power up)	V _O = 0.5 V	OE at 0.8 V			-0.6	mA	
loz			V _O = 2.7 V				70	μΑ	
		$V_{CC} = 1.8 \text{ V to 0 (power down)}$	V _O = 0.5 V	OE at 0.8 V			-0.6	mA	
	A and B ports	V 0. 55V					0.25		
l _l	DIR and OE	$V_{CC} = 0 \text{ to } 5.5 \text{ V},$	$V_{I} = 5.5 \text{ V}$			0.1	mA		
. +	A and B ports	v 55V					70		
I _{IH} ‡	DIR and OE	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V				20	μΑ	
. +	A and B ports	v 55V	V _I = 0.5 V				2.0		
I _{IL} ‡	DIR and OE	$V_{CC} = 5.5 \text{ V},$					-0.6	mA	
los§	B port¶	V _{CC} = 5.5 V,	V _O = 0		-60		-150	mA	
	A to B port					48	60		
ICCL	B to A port	V _{CC} = 5.5 V			95	125	mA		
	A to B port	v 55V				36	46		
ICCH	B to A port	V _{CC} = 5.5 V				63	80	mA	
ICCZ		V _{CC} = 5.5 V				12	16	mA	
Ci	OE and DIR	V _{CC} = 5.5 V,	V _I = 2.5 V to 0.5 V			8		рF	
0	A port	V 55V	V _I = 2.5 V to 0.5 V			18			
C _{io}	B port	$V_{CC} = 5.5 \text{ V},$			8			pF	

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C. ‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state outputs current. § Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

[¶] Testing for this parameter on the A port is not recommended.

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switching characteristics (see Note 2)

PARAMETER	FROM	то	V_{CC} = 5 V, C_L = 50 pF, $R1$ = 500 Ω , $R2$ = 500 Ω , T_A = 25°C			V_{CC} = 4.5 V to 5.5 V, C_L = 50 pF, R1 = 500 Ω, R2 = 500 Ω				UNIT
7,117,1112,121	(INPUT)	(OUTPUT)				T _A = -40°C to 85°C		$T_A = 25^{\circ}C$ $ I_A = -40^{\circ}C I_A = 0^{\circ}C$		
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
^t PLH	А	Б	1.2	3.3	5.1	1.2	5.7	1.2	5.7	
^t PHL		В	1.9	4.3	6.7	1.9	7.3	1.9	7.2	ns
^t PLH	В	А	1.2	3.3	4.8	1.2	5.5	1.2	5.5	ns
^t PHL	Ь		2.1	4	5.6	2.1	6.3	2.1	6.2	
^t PZH	ŌĒ	<u></u>	3.7	6.3	8.4	3.7	9.7	3.7	9.6	20
t _{PZL}	OE	А	4.5	7.4	9.2	4.5	10.6	4.5	10.3	ns
^t PHZ	ŌĒ	^	1.8	3.7	5.5	1.8	6.2	1.8	6.2	
t _{PLZ}	OE	А	3.3	5.1	7.2	3.3	8.8	3.3	8.3	ns
^t PZH	ŌĒ	В	3.4	5.7	7.9	3.4	8.9	3.4	8.9	20
^t PZL		В	4.3	6.6	8.7	4.3	9.9	4.3	9.7	ns
^t PHZ	ŌĒ	В	2.7	4.5	6.3	2.7	6.9	2.7	6.9	ns
t _{PLZ}		OE	D	1.7	4.5	6.8	1.7	7.7	1.7	7.5

NOTE 2: Load circuits and voltage waveforms are shown in Section 1.

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PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SN64BCT25245DW	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT25245
SN64BCT25245DW.A	Active	Production	SOIC (DW) 24	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	6BCT25245

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

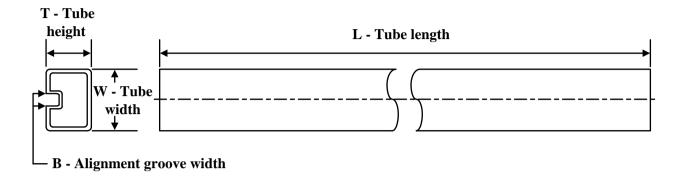
⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

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TUBE

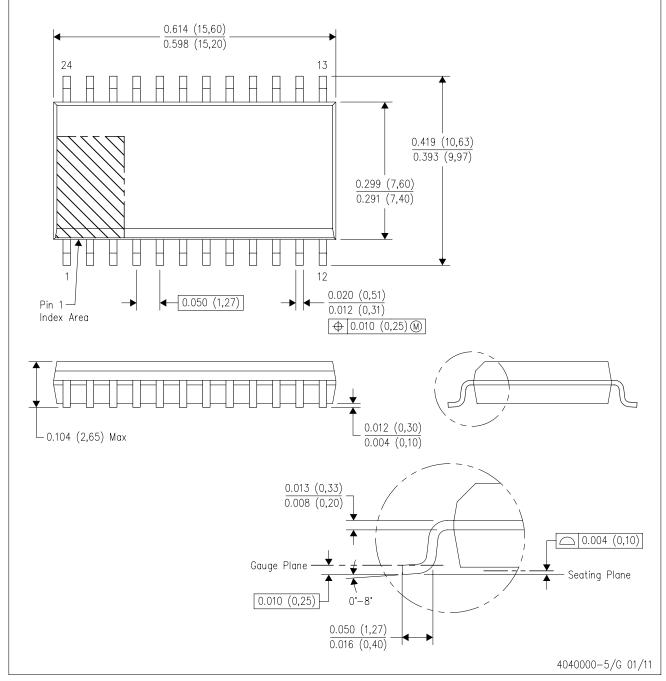


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN64BCT25245DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN64BCT25245DW.A	DW	SOIC	24	25	506.98	12.7	4826	6.6

DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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Last updated 10/2025